

HPF-18-01-T-S

HPF-10-02-T-S

HPF SERIES

(5,08 mm) .200"

POWER SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HPF

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Sn over

50µ" (1,27 µm) Ni

Insertion Depth:

(3,68 mm) .145" to (8,26 mm) .325" (.368" (9,35 mm) plus board thickness minimum for bottom entry)

Wiping Distance:

(0,38 mm) .015"

Insertion Force:

(Single contact only)

56 oz (15,57 N) avg.

Withdrawal Force:

(Single contact only)

52 oz (14,46 N) avg.

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,15 mm) .006" max (02-10)

(0,20 mm) .008" max (11-20)

RoHS Compliant:

Yes

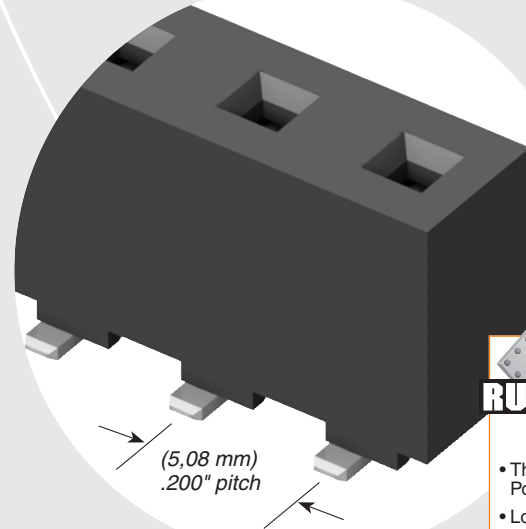
Mates with:
HPM, HPW

POWER EYE CONTACT



HPF/HPM	
PINS	CURRENT RATING (PER CONTACT)
1	16.6 A
2	14.4 A
3	13.2 A
4	12.7 A
ALL	8.9 A

Surface Mount
or
Through-hole



(5,08 mm)
.200" pitch

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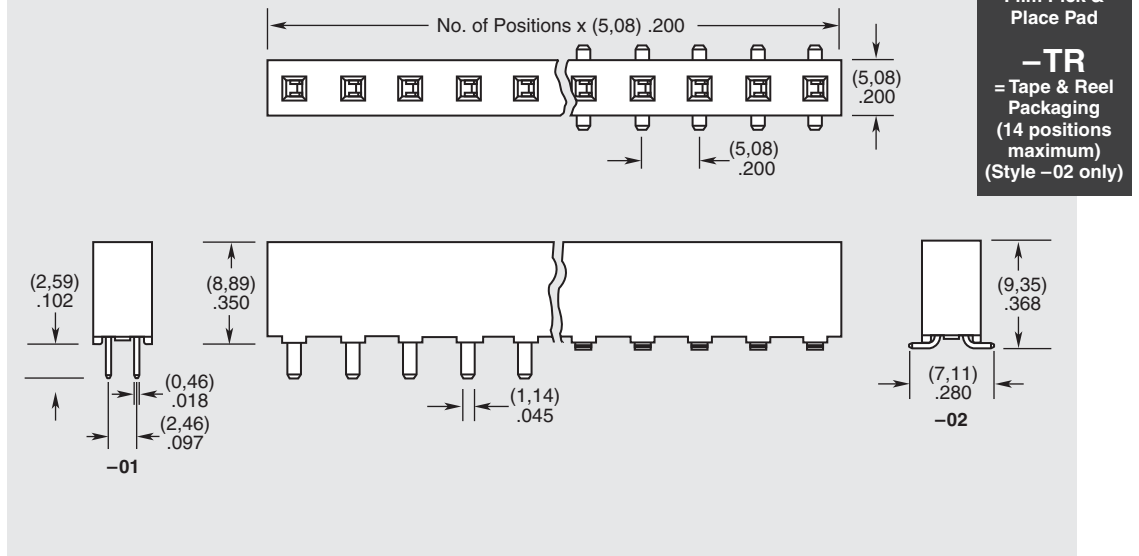
- Three-finger Power Eye contact
- Locking clip option

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



HPF	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	S	OTHER OPTIONS
	02 thru 20	-01 = Through-hole	-T = Matte Tin		-LC = Locking Clip (Manual placement required) (Style -02 only)
		-02 = Surface Mount			-K = (6,50 mm) .256" DIA Polyimide Film Pick & Place Pad
					-TR = Tape & Reel Packaging (14 positions maximum) (Style -02 only)



Note: Some lengths, styles and options are non-standard, non-returnable.